

Dual-4 A, High-Speed, Low-Side Gate Drivers

FAN3213, FAN3214

Description

The FAN3213 and FAN3214 dual 4 A gate drivers are designed to drive N-channel enhancement-mode MOSFETs in low-side switching applications by providing high peak current pulses during the short switching intervals. They are both available with TTL input thresholds. Internal circuitry provides an under-voltage lockout function by holding the output LOW until the supply voltage is within the operating range. In addition, the drivers feature matched internal propagation delays between A and B channels for applications requiring dual gate drives with critical timing, such as synchronous rectifiers. This also enables connecting two drivers in parallel to effectively double the current capability driving a single MOSFET.

The FAN3213/14 drivers incorporate MillerDrive™ architecture for the final output stage. This bipolar-MOSFET combination provides high current during the Miller plateau stage of the MOSFET turn-on/turn-off process to minimize switching loss, while providing rail-to-rail voltage swing and reverse current capability.

The FAN3213 offers two inverting drivers and the FAN3214 offers two non-inverting drivers. Both are offered in a standard 8-pin SOIC package.

Features

- Industry-Standard Pin Out
- 4.5 to 18 V Operating Range
- 5 A Peak Sink/Source at $V_{DD} = 12\text{ V}$
- 4.3 A Sink/2.8 A Source at $V_{OUT} = 6\text{ V}$
- TTL Input Thresholds
- Two Versions of Dual Independent Drivers:
 - ◆ Dual Inverting (FAN3213)
 - ◆ Dual Non-Inverting (FAN3214)
- Internal Resistors Turn Driver Off if No Inputs
- Miller Drive Technology
- 12 ns/9 ns Typical Rise/Fall Times with 2.2 nF Load
- Typical Propagation Delay Under 20 ns Matched within 1 ns to the Other Channel
- Double Current Capability by Paralleling Channels
- Standard SOIC-8 Package
- Rated from $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$ Ambient
- These are Pb-Free Devices

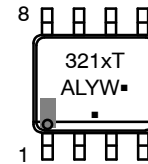
Applications

- Switch-Mode Power Supplies
- High-Efficiency MOSFET Switching
- Synchronous Rectifier Circuits
- DC-to-DC Converters
- Motor Control



SOIC8
CASE 751EB

MARKING DIAGRAM



A	= Assembly Location
L	= Wafer Lot
YW	= Assembly Start Week
▪	= Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information on page 15 of this data sheet.

NOTE: Some of the devices on this data sheet have been **DISCONTINUED**. Please refer to the table on page 15.

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PIN CONFIGURATIONS

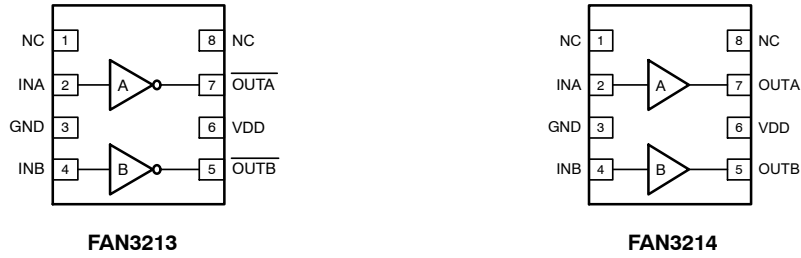


Figure 1. Pin Configurations

PACKAGE OUTLINES

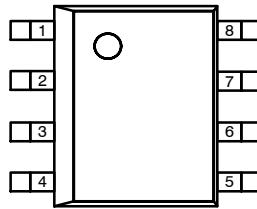


Figure 2. SOIC-8 (Top View)

THERMAL CHARACTERISTICS (Note 1)

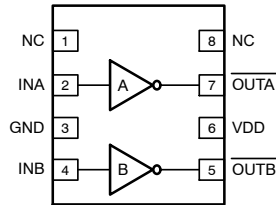
Package	θ_{JL} (Note 2)	θ_{JT} (Note 3)	θ_{JA} (Note 4)	Ψ_{JB} (Note 5)	Ψ_{JT} (Note 6)	Unit
8-Pin Small Outline Integrated Circuit (SOIC)	38	29	87	41	2.3	$^{\circ}\text{C}/\text{W}$

1. Estimates derived from thermal simulation; actual values depend on the application.
2. θ_{JL} (θ_{JL}): Thermal resistance between the semiconductor junction and the bottom surface of all the leads (including any thermal pad) that are typically soldered to a PCB.
3. θ_{JT} (θ_{JT}): Thermal resistance between the semiconductor junction and the top surface of the package, assuming it is held at a uniform temperature by a top-side heatsink.
4. θ_{JA} (θ_{JA}): Thermal resistance between junction and ambient, dependent on the PCB design, heat sinking, and airflow. The value given is for natural convection with no heatsink using a 2S2P board, as specified in JEDEC standards JESD51-2, JESD51-5, and JESD51-7, as appropriate.
5. Ψ_{JB} (Ψ_{JB}): Thermal characterization parameter providing correlation between semiconductor junction temperature and an application circuit board reference point for the thermal environment defined in Note 4. For the MLP-8 package, the board reference is defined as the PCB copper connected to the thermal pad and protruding from either end of the package. For the SOIC-8 package, the board reference is defined as the PCB copper adjacent to pin 6.
6. Ψ_{JT} (Ψ_{JT}): Thermal characterization parameter providing correlation between the semiconductor junction temperature and the center of the top of the package for the thermal environment defined in Note 4.

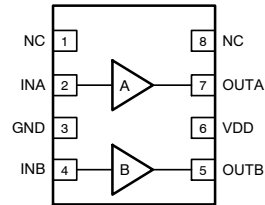
FAN3213, FAN3214

PIN DEFINITIONS

Pin	Name	Description
1	NC	No Connect. This pin can be grounded or left floating.
2	INA	Input to Channel A.
3	GND	Ground. Common ground reference for input and output circuits.
4	INB	Input to Channel B.
5	OUTB	Gate Drive Output B (inverted from the input): Held LOW unless required input is present and V_{DD} is above UVLO threshold.
5	OUTB	Gate Drive Output B: Held LOW unless required input(s) are present and V_{DD} is above UVLO threshold.
6	VDD	Supply Voltage. Provides power to the IC.
7	OUTA	Gate Drive Output A (inverted from the input): Held LOW unless required input is present and V_{DD} is above UVLO threshold.
7	OUTA	Gate Drive Output A: Held LOW unless required input(s) are present and V_{DD} is above UVLO threshold.
8	NC	No Connect. This pin can be grounded or left floating.



FAN3213



FAN3214

Figure 3. Pin Configurations (Repeated)

OUTPUT LOGIC

FAN3213 (x = A or B)	
INx	OUTx
0	1
1 (Note 7)	0

FAN3214 (x = A or B)	
INx	OUTx
0 (Note 7)	0
1	1

7. Default input signal if no external connection is made.

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BLOCK DIAGRAMS

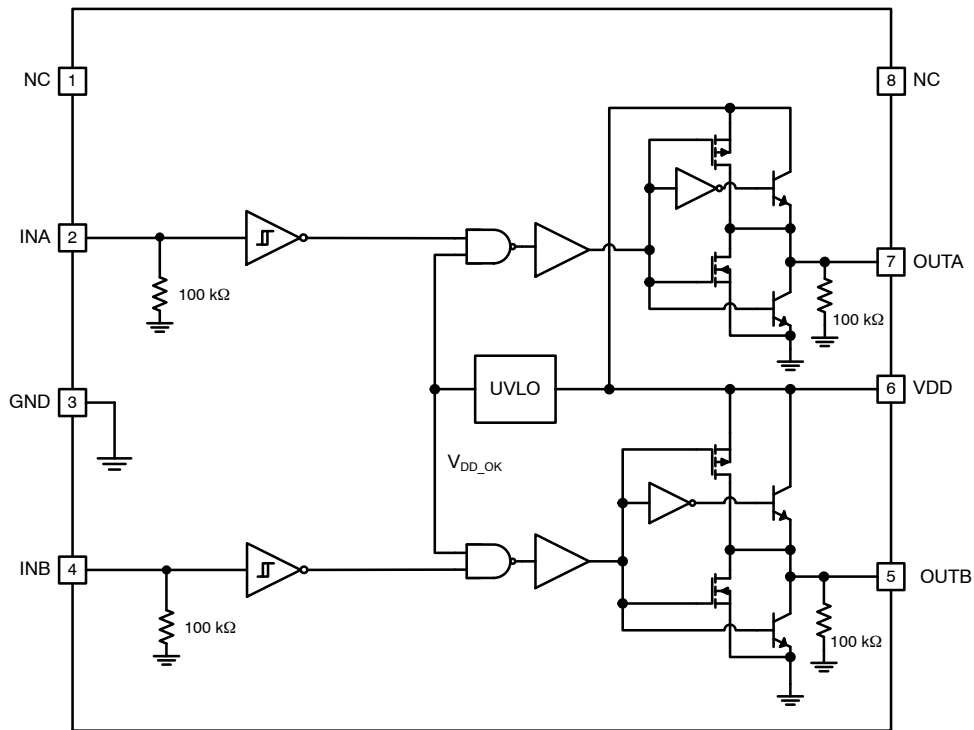


Figure 4. FAN3213 Block Diagram

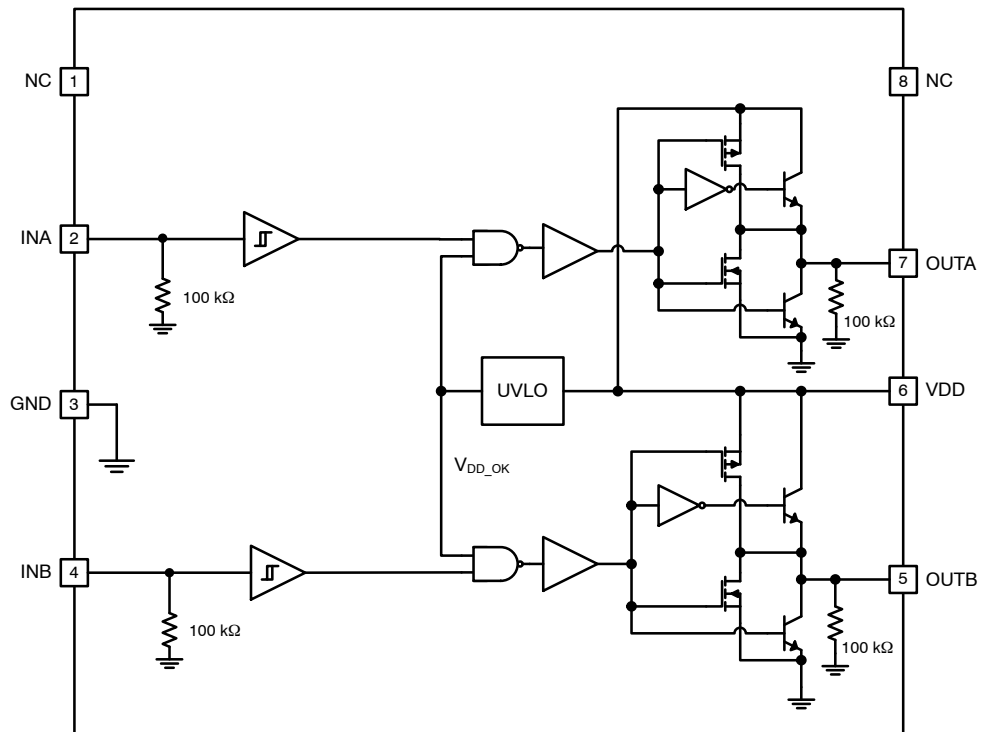


Figure 5. FAN3214 Block Diagram

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ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Min	Max	Unit
V_{DD}	VDD to GND	-0.3	20.0	V
V_{IN}	INA and INB to GND	GND - 0.3	$V_{DD} + 0.3$	V
V_{OUT}	OUTA and OUTB to GND	GND - 0.3	$V_{DD} + 0.3$	V
T_L	Lead Soldering Temperature (10 Seconds)	-	+260	°C
T_J	Junction Temperature	-55	+150	°C
T_{STG}	Storage Temperature	-65	+150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V_{DD}	Supply Voltage Range	4.5	18.0	V
V_{IN}	Input Voltage INA and INB	0	V_{DD}	V
T_A	Operating Ambient Temperature	-40	+125	°C

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

ELECTRICAL CHARACTERISTICS ($V_{DD} = 12\text{ V}$ and $T_J = -40\text{ °C}$ to $+125\text{ °C}$ unless otherwise noted. Currents are defined as positive into the device and negative out of the device.)

Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
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SUPPLY

V_{DD}	Operating Range		4.5	-	18.0	V
I_{DD}	Supply Current, Inputs Not Connected		-	0.70	0.95	mA
V_{ON}	Turn-On Voltage	INA = V_{DD} , INB = 0 V	3.5	3.9	4.3	V
V_{OFF}	Turn-Off Voltage	INA = V_{DD} , INB = 0 V	3.3	3.7	4.1	V

INPUTS

V_{IL_T}	INx Logic Low Threshold		0.8	1.2	-	V
V_{IH_T}	INx Logic High Threshold		-	1.6	2.0	V
I_{IN+}	Non-Inverting Input Current	IN from 0 to V_{DD}	-1.5	-	175	μA
I_{IN-}	Inverting Input Current	IN from 0 to V_{DD}	-175	-	1.5	μA
V_{HYS_T}	TTL Logic Hysteresis Voltage		0.2	0.4	0.8	V

OUTPUTS

I_{SINK}	OUT Current, Mid-Voltage, Sinking (Note 8)	OUTx at $V_{DD} / 2$, $C_{LOAD} = 0.22\text{ μF}$, $f = 1\text{ kHz}$	-	4.3	-	A
I_{SOURCE}	OUT Current, Mid-Voltage, Sourcing (Note 8)	OUTx at $V_{DD} / 2$, $C_{LOAD} = 0.22\text{ μF}$, $f = 1\text{ kHz}$	-	-2.8	-	A
I_{PK_SINK}	OUT Current, Peak, Sinking (Note 8)	$C_{LOAD} = 0.22\text{ μF}$, $f = 1\text{ kHz}$	-	5	-	A
I_{PK_SOURCE}	OUT Current, Peak, Sourcing (Note 8)	$C_{LOAD} = 0.22\text{ μF}$, $f = 1\text{ kHz}$	-	-5	-	A
I_{RVS}	Output Reverse Current Withstand (Note 8)		-	500	-	mA
T_{DEL_MATCH}	Propagation Matching Between Channels	INA = INB, OUTA and OUTB at 50% Point	-	2	4	ns
t_{RISE}	Output Rise Time (Note 9)	$C_{LOAD} = 2200\text{ pF}$	-	12	20	ns

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ELECTRICAL CHARACTERISTICS ($V_{DD} = 12\text{ V}$ and $T_J = -40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$ unless otherwise noted. Currents are defined as positive into the device and negative out of the device.) (continued)

Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
OUTPUTS						
t_{FALL}	Output Fall Time (Note 9)	$C_{LOAD} = 2200\text{ pF}$	–	9	17	ns
t_{D1}, t_{D2}	Output Propagation Delay, TTL Inputs (Note 9)	$0-5\text{ V}_{IN}, 1\text{ V/ns}$ Slew Rate	9	17	29	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

8. Not tested in production.

9. See Timing Diagrams of Figure 6 and Figure 7.

TIMING DIAGRAMS

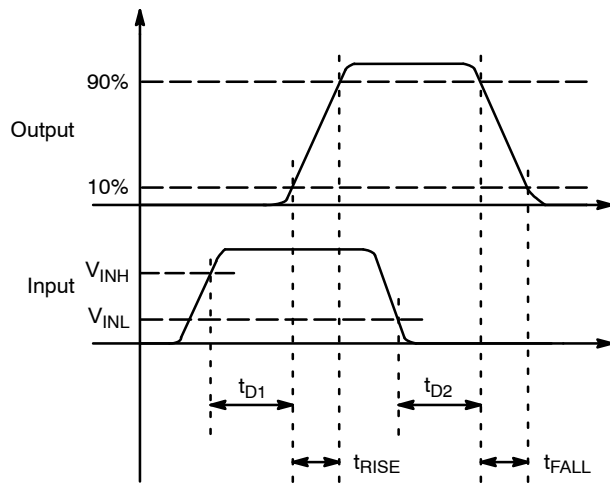


Figure 6. Non-Inverting

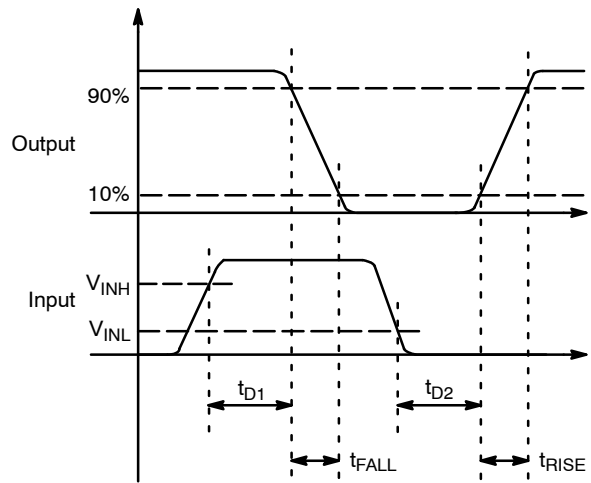


Figure 7. Inverting

TYPICAL PERFORMANCE CHARACTERISTICS

(TYPICAL CHARACTERISTICS ARE PROVIDED AT $T_A = 25^\circ\text{C}$ AND $V_{DD} = 12\text{ V}$ UNLESS OTHERWISE NOTED)

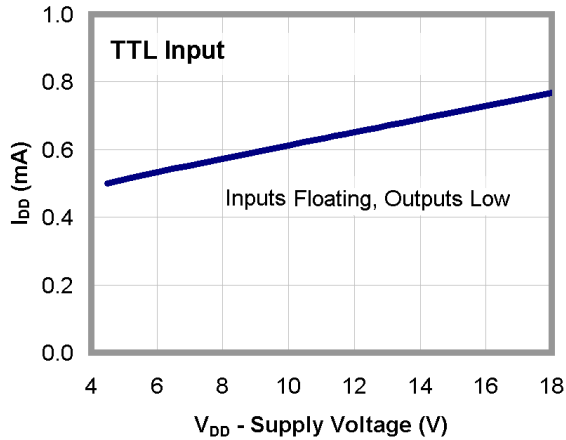


Figure 8. I_{DD} (Static) vs. Supply Voltage (Note 10)

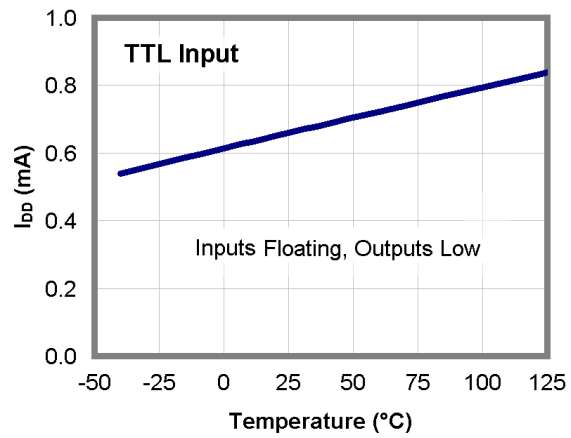


Figure 9. I_{DD} (Static) vs. Supply Voltage (Note 10)

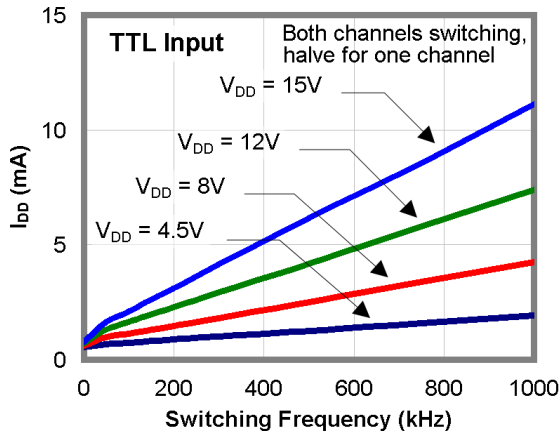


Figure 10. I_{DD} (No-Load) vs. Frequency

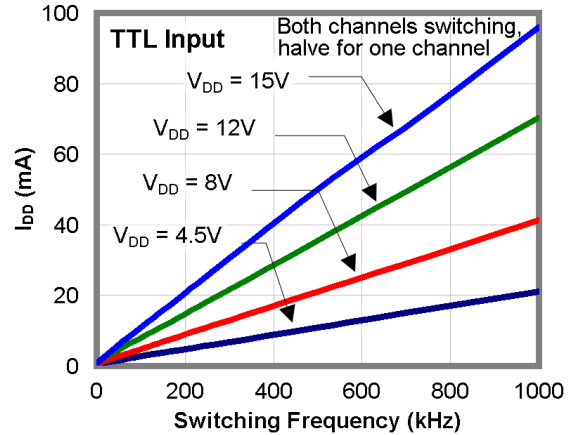


Figure 11. I_{DD} (No-Load) vs. Frequency

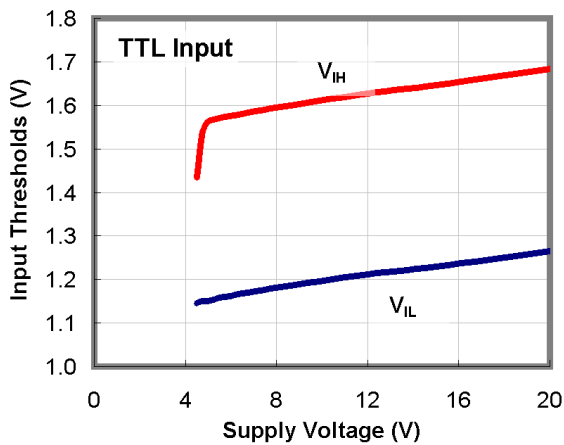


Figure 12. Input Thresholds vs. Supply Voltage

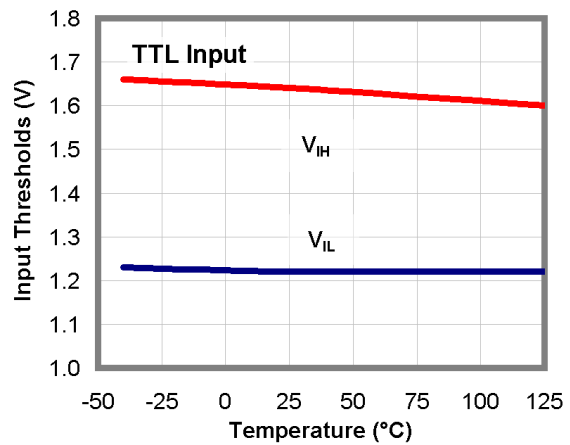


Figure 13. Input Thresholds vs. Supply Voltage

TYPICAL PERFORMANCE CHARACTERISTICS

(TYPICAL CHARACTERISTICS ARE PROVIDED AT $T_A = 25^\circ\text{C}$ AND $V_{DD} = 12\text{ V}$ UNLESS OTHERWISE NOTED) (CONTINUED)

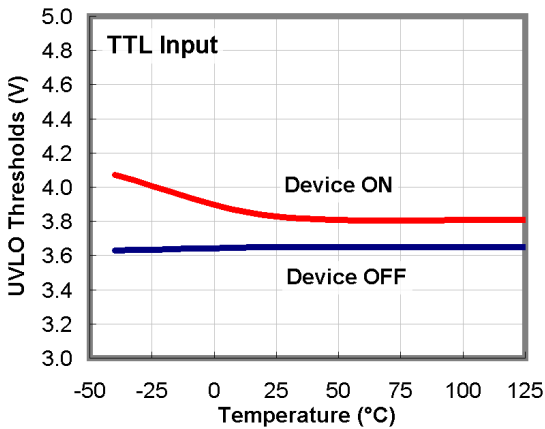


Figure 14. UVLO Thresholds vs. Temperature

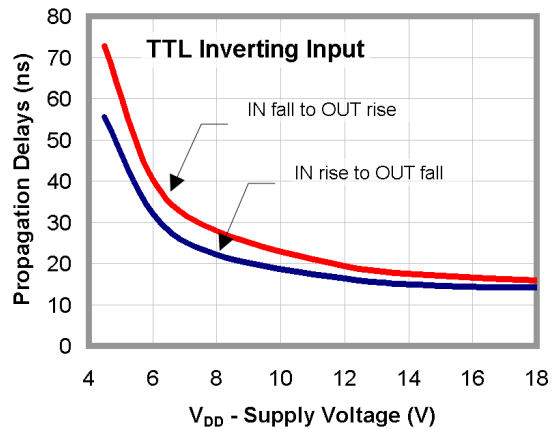


Figure 15. Propagation Delay vs. Supply Voltage

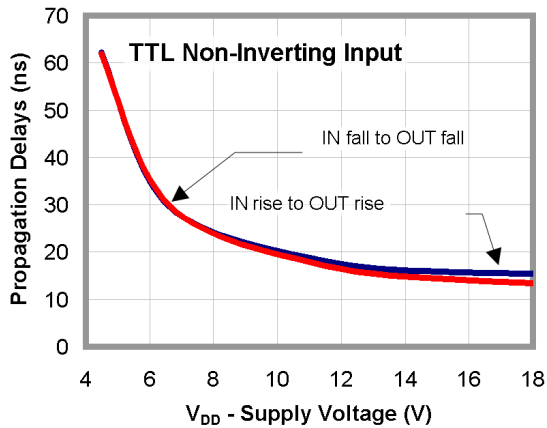


Figure 16. Propagation Delay vs. Supply Voltage

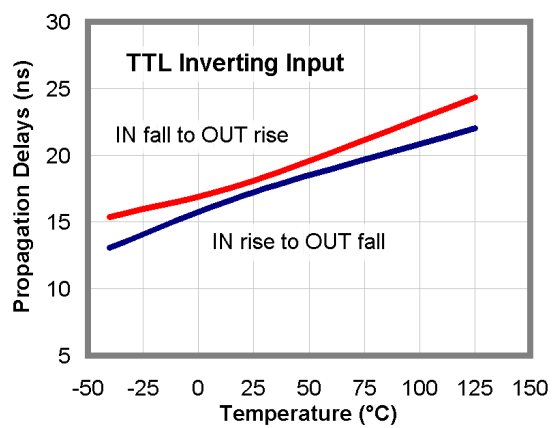


Figure 17. Propagation Delay vs. Supply Voltage

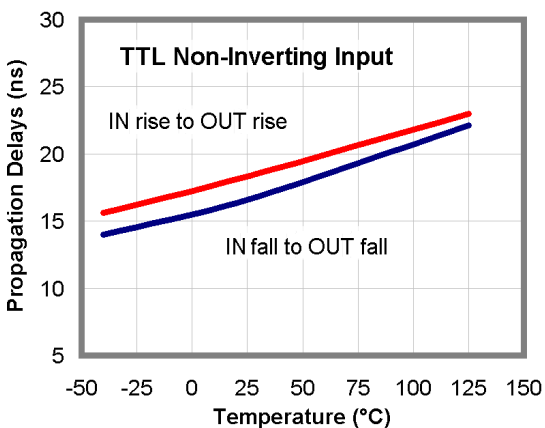


Figure 18. Propagation Delay vs. Supply Voltage

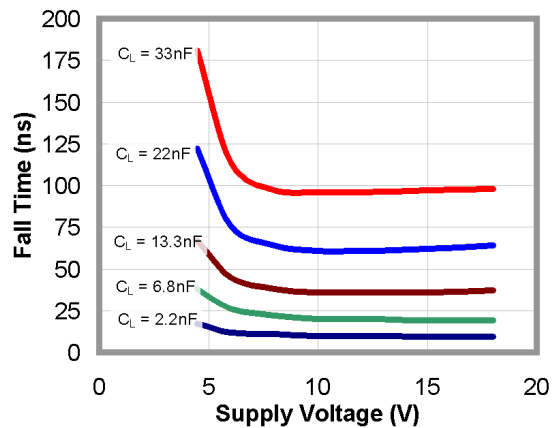


Figure 19. Fall Time vs. Supply Voltage

TYPICAL PERFORMANCE CHARACTERISTICS

(TYPICAL CHARACTERISTICS ARE PROVIDED AT $T_A = 25^\circ\text{C}$ AND $V_{DD} = 12\text{ V}$ UNLESS OTHERWISE NOTED) (CONTINUED)

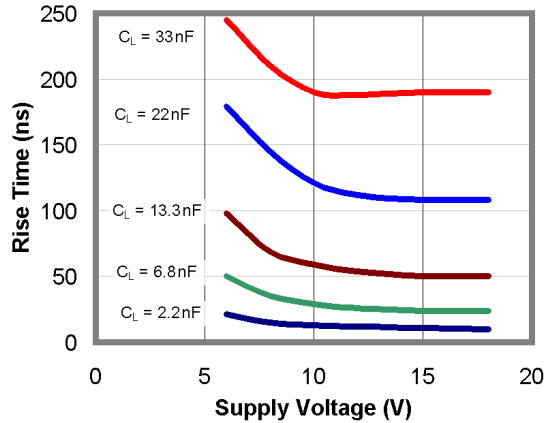


Figure 20. Rise Time vs. Supply Voltage

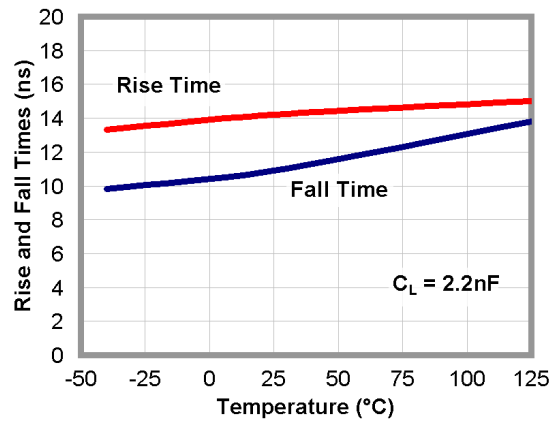


Figure 21. Rise and Fall Time vs. Temperature

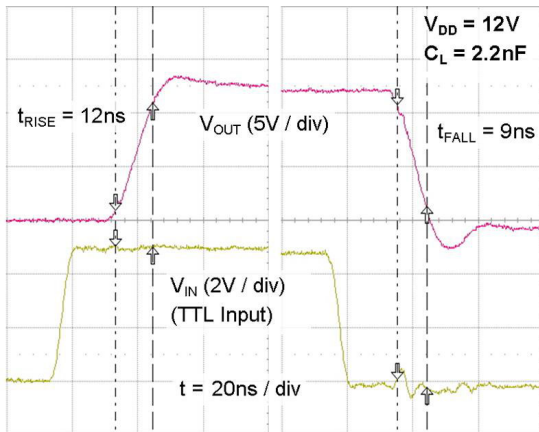


Figure 22. Rise / Fall Waveforms with 2.2 nF Load

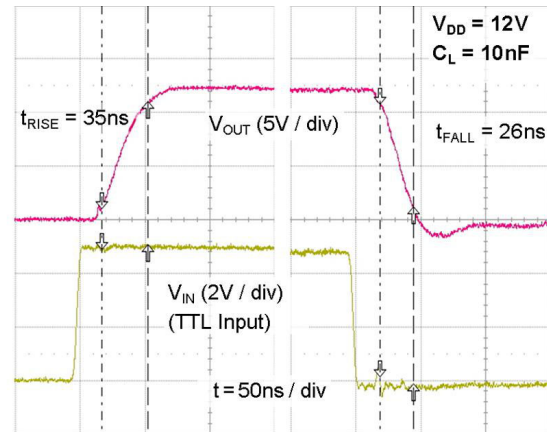


Figure 23. Rise / Fall Waveforms with 10 nF Load

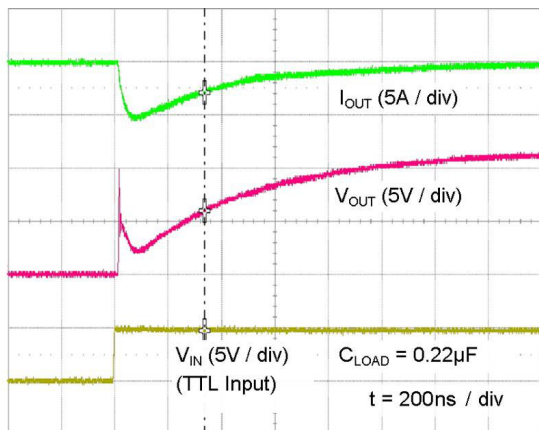


Figure 24. Quasi-Static Source Current with $V_{DD} = 12\text{ V}$ (Note 11)

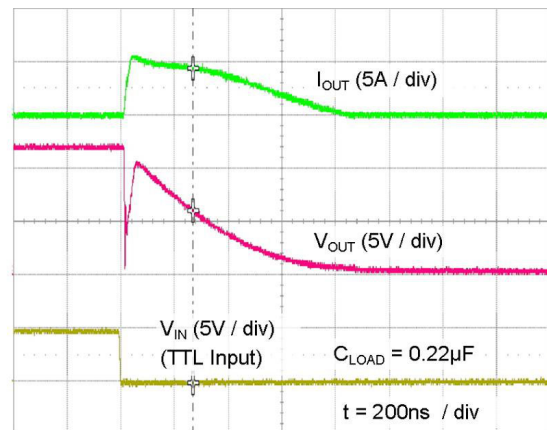


Figure 25. Quasi-Static Sink Current with $V_{DD} = 12\text{ V}$ (Note 11)

TYPICAL PERFORMANCE CHARACTERISTICS

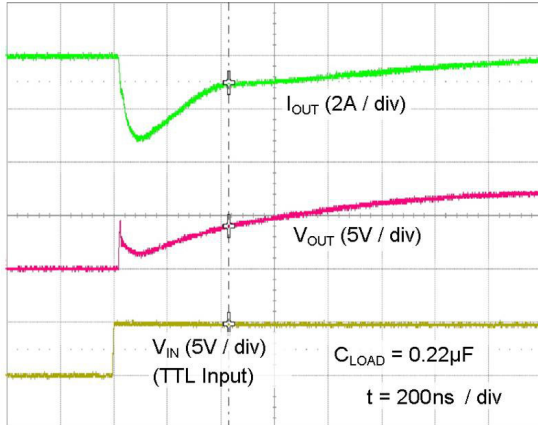
(TYPICAL CHARACTERISTICS ARE PROVIDED AT $T_A = 25^\circ\text{C}$ AND $V_{DD} = 12\text{ V}$ UNLESS OTHERWISE NOTED) (CONTINUED)

Figure 26. Quasi-Static Source Current with $V_{DD} = 8\text{ V}$ (Note 11)

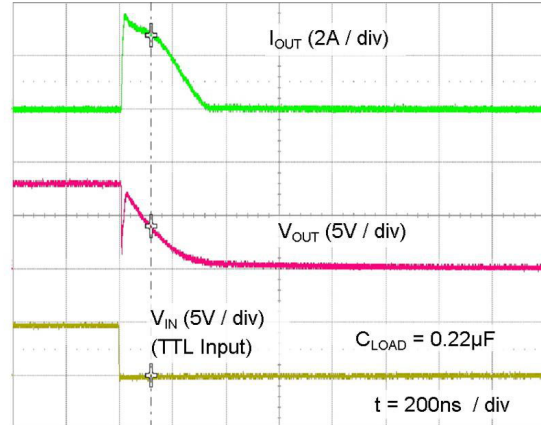


Figure 27. Quasi-Static Sink Current with $V_{DD} = 8\text{ V}$ (Note 11)

10. For any inverting inputs pulled low, non-inverting inputs pulled high, or outputs driven high; static I_{DD} increases by the current flowing through the corresponding pull-up/down resistor shown in Figure 4 and Figure 5.
11. The initial spike in each current waveform is a measurement artifact caused by the stray inductance of the current-measurement loop.

TEST CIRCUIT

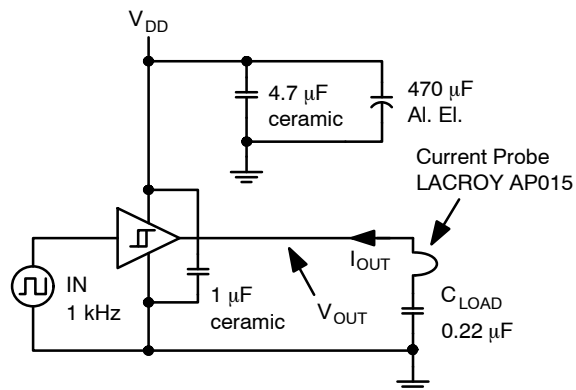


Figure 28. Quasi-Static I_{OUT} / V_{OUT} Test Circuit

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If circuit noise affects normal operation, the value of C_{BYP} may be increased, to 50–100 times the C_{EQV} , or C_{BYP} may be split into two capacitors. One should be a larger value, based on equivalent load capacitance, and the other a smaller value, such as 1–10 nF mounted closest to the VDD and GND pins to carry the higher-frequency components of the current pulses. The bypass capacitor must provide the pulsed current from both of the driver channels and, if the drivers are switching simultaneously, the combined peak current sourced from the C_{BYP} would be twice as large as when a single channel is switching.

Layout and Connection Guidelines

The FAN3213 and FAN3214 gate drivers incorporate fast-reacting input circuits, short propagation delays, and powerful output stages capable of delivering current peaks over 4 A to facilitate voltage transition times from under 10 ns to over 150 ns. The following layout and connection guidelines are strongly recommended:

- Keep high-current output and power ground paths separate from logic input signals and signal ground paths. This is especially critical for TTL-level logic thresholds at driver input pins.
- Keep the driver as close to the load as possible to minimize the length of high-current traces. This reduces the series inductance to improve high-speed switching, while reducing the loop area that can radiate EMI to the driver inputs and surrounding circuitry.
- If the inputs to a channel are not externally connected, the internal 100 k Ω resistors indicated on block diagrams command a low output. In noisy environments, it may be necessary to tie inputs of an unused channel to VDD or GND using short traces to prevent noise from causing spurious output switching.
- Many high-speed power circuits can be susceptible to noise injected from their own output or other external sources, possibly causing output re-triggering. These effects can be obvious if the circuit is tested in breadboard or non-optimal circuit layouts with long input or output leads. For best results, make connections to all pins as short and direct as possible.
- FAN3213 and FAN3214 are pin-compatible with many other industry-standard drivers.
- The turn-on and turn-off current paths should be minimized, as discussed in the following section.

Figure 30 shows the pulsed gate drive current path when the gate driver is supplying gate charge to turn the MOSFET on. The current is supplied from the local bypass capacitor, C_{BYP} , and flows through the driver to the MOSFET gate and to ground. To reach the high peak currents possible, the resistance and inductance in the path should be minimized. The localized C_{BYP} acts to contain the high peak current pulses within this driver-MOSFET circuit, preventing them from disturbing the sensitive analog circuitry in the PWM controller.

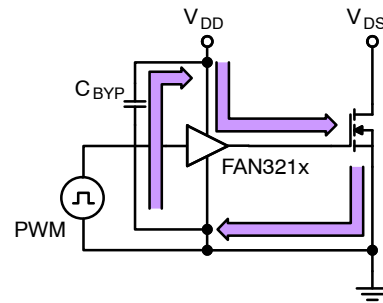


Figure 30. Current Path for MOSFET Turn-On

Figure 31 shows the current path when the gate driver turns the MOSFET OFF. Ideally, the driver shunts the current directly to the source of the MOSFET in a small circuit loop. For fast turn-off times, the resistance and inductance in this path should be minimized.

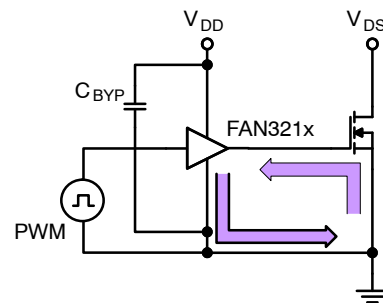


Figure 31. Current Path for MOSFET Turn-Off

Operational Waveforms

At power-up, the driver output remains LOW until the V_{DD} voltage reaches the turn-on threshold. The magnitude of the OUT pulses rises with V_{DD} until steady-state V_{DD} is reached. The non-inverting operation illustrated in Figure 32 shows that the output remains LOW until the UVLO threshold is reached, then the output is in-phase with the input.

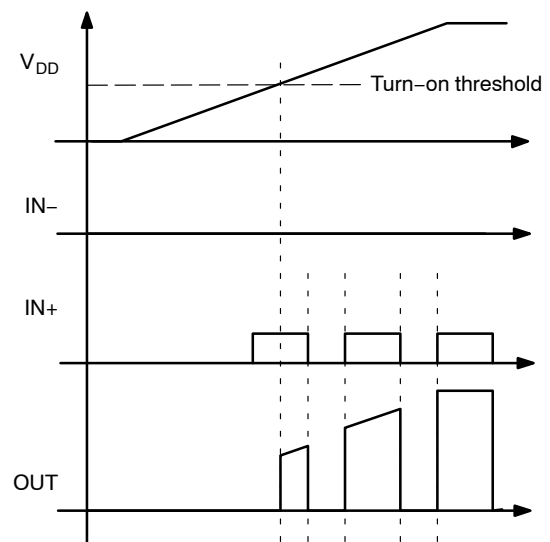


Figure 32. Non-Inverting Startup Waveforms

The inverting configuration of startup waveforms are shown in Figure 33. With IN+ tied to V_{DD} and the input signal applied to IN–, the OUT pulses are inverted with respect to the input. At power-up, the inverted output remains LOW until the V_{DD} voltage reaches the turn-on threshold, then it follows the input with inverted phase.

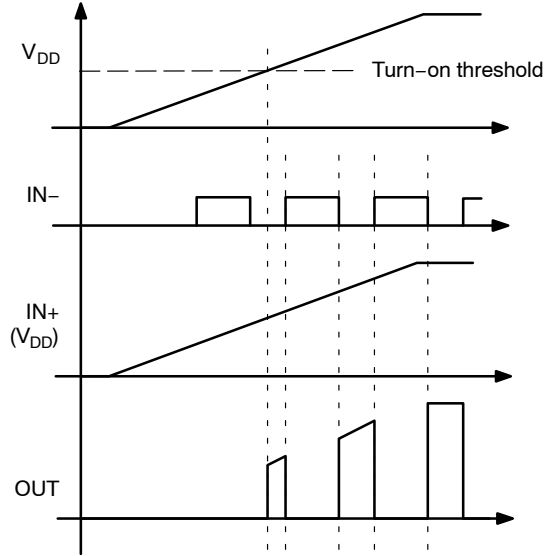


Figure 33. Inverting Startup Waveforms

Thermal Guidelines

Gate drivers used to switch MOSFETs and IGBTs at high frequencies can dissipate significant amounts of power. It is important to determine the driver power dissipation and the resulting junction temperature in the application to ensure that the part is operating within acceptable temperature limits.

The total power dissipation in a gate driver is the sum of two components, P_{GATE} and P_{DYNAMIC}:

$$P_{TOTAL} = P_{GATE} + P_{DYNAMIC} \quad (\text{eq. 1})$$

P_{GATE} (Gate Driving Loss): The most significant power loss results from supplying gate current (charge per unit time) to switch the load MOSFET on and off at the switching frequency. The power dissipation that results from driving a MOSFET at a specified gate-source voltage, V_{GS}, with gate charge, Q_G, at switching frequency, f_{SW}, is determined by:

$$P_{GATE} = Q_G \cdot V_{GS} \cdot f_{SW} \cdot n \quad (\text{eq. 2})$$

where n is the number of driver channels in use (1 or 2).

P_{DYNAMIC} (Dynamic Pre-Drive/Shoot-through Current): A power loss resulting from internal current consumption

under dynamic operating conditions, including pin pull-up/pull-down resistors. The internal current consumption (I_{DYNAMIC}) can be estimated using the graphs in Figure 10 of the Typical Performance Characteristics to determine the current I_{DYNAMIC} drawn from V_{DD} under actual operating conditions:

$$P_{DYNAMIC} = I_{DYNAMIC} \cdot V_{DD} \cdot n \quad (\text{eq. 3})$$

where n is the number of driver ICs in use. Note that n is usually be one IC even if the IC has two channels, unless two or more driver ICs are in parallel to drive a large load.

Once the power dissipated in the driver is determined, the driver junction rise with respect to circuit board can be evaluated using the following thermal equation, assuming ψ_{JB} was determined for a similar thermal design (heat sinking and air flow):

$$T_J = P_{TOTAL} \cdot \Psi_{JB} + T_B \quad (\text{eq. 4})$$

where:

T_J = driver junction temperature;

ψ_{JB} = (psi) thermal characterization parameter relating temperature rise to total power dissipation; and

T_B = board temperature in location as defined in the [Thermal Characteristics](#) table.

To give a numerical example, assume for a 12 V VDD (Vibas) system, the synchronous rectifier switches of Figure 34 have a total gate charge of 60 nC at V_{GS} = 7 V. Therefore, two devices in parallel would have 120 nC gate charge. At a switching frequency of 300 kHz, the total power dissipation is:

$$P_{GATE} = 120 \text{ nC} \cdot 7 \text{ V} \cdot 300 \text{ kHz} \cdot 2 = 0.504 \text{ W} \quad (\text{eq. 5})$$

$$P_{DYNAMIC} = 3.0 \text{ mA} \cdot 12 \text{ V} \cdot 1 = 0.036 \text{ W} \quad (\text{eq. 6})$$

$$P_{TOTAL} = 0.540 \text{ W} \quad (\text{eq. 7})$$

The SOIC-8 has a junction-to-board thermal characterization parameter of ψ_{JB} = 42 °C/W. In a system application, the localized temperature around the device is a function of the layout and construction of the PCB along with airflow across the surfaces. To ensure reliable operation, the maximum junction temperature of the device must be prevented from exceeding the maximum rating of 150 °C; with 80% derating, T_J would be limited to 120 °C. Rearranging Equation 4 determines the board temperature required to maintain the junction temperature below 120 °C:

$$T_{B,MAX} = T_J - P_{TOTAL} \cdot \Psi_{JB} \quad (\text{eq. 8})$$

$$T_{B,MAX} = 120^\circ\text{C} - 0.54 \text{ W} \cdot 42^\circ\text{C/W} = 97^\circ\text{C} \quad (\text{eq. 9})$$

TYPICAL APPLICATION DIAGRAMS

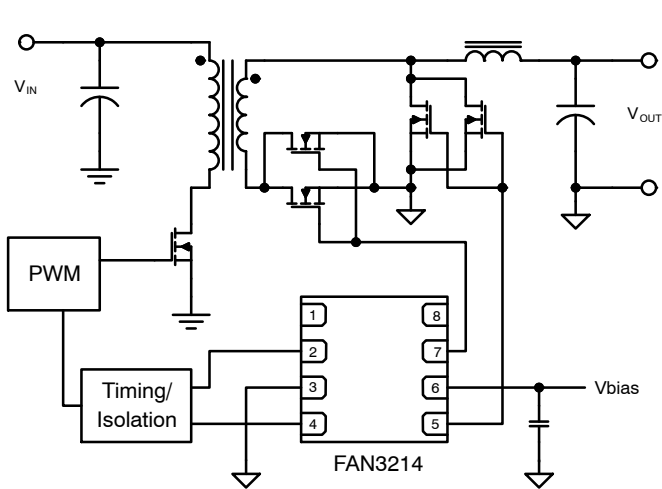


Figure 34. High-Current Forward Converter with Synchronous Rectification

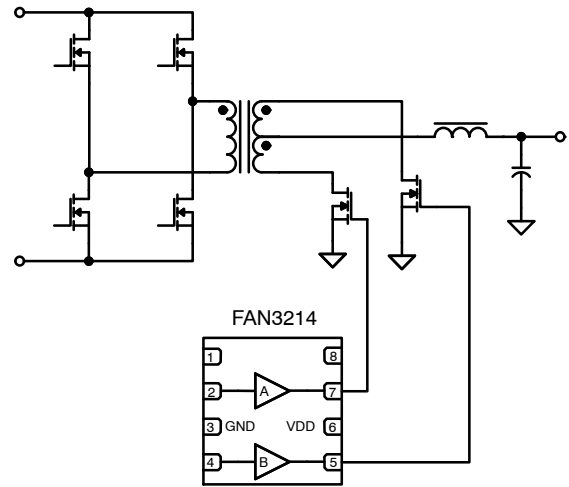


Figure 35. Center-Tapped Bridge Output with Synchronous Rectifiers

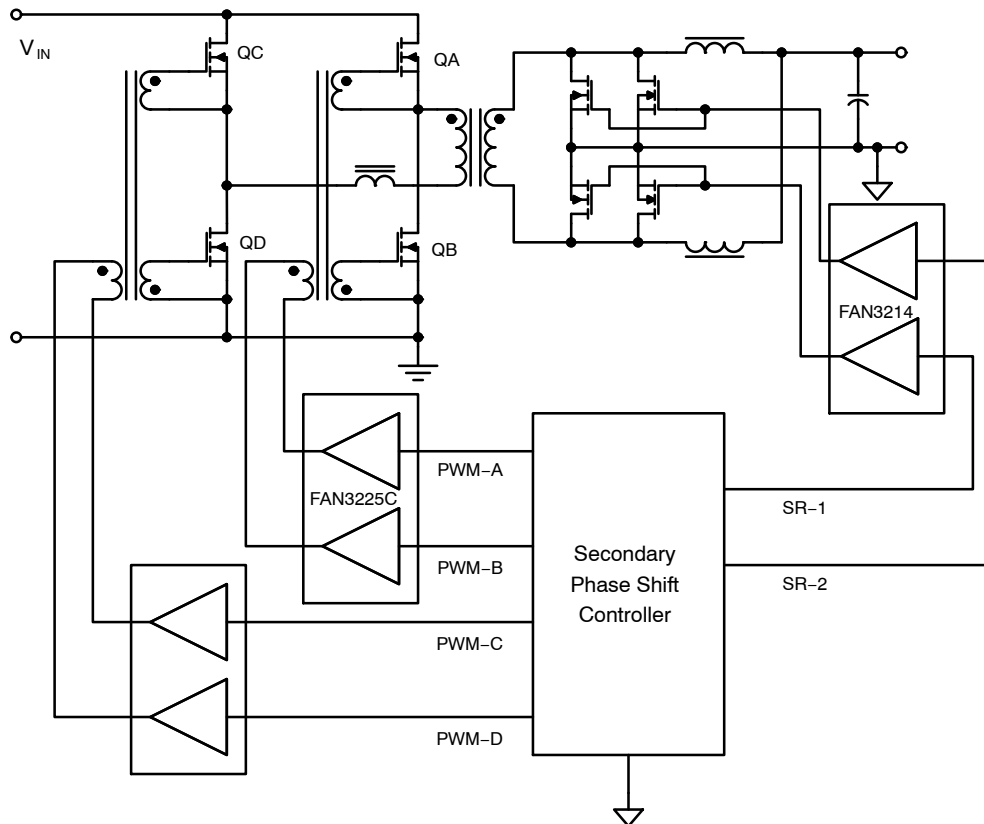


Figure 36. Secondary Controlled Full Bridge with Current Doubler Output, Synchronous Rectifiers (Simplified)

FAN3213, FAN3214

ORDERING INFORMATION

Part Number	Logic	Input Threshold	Package	Shipping [†]
FAN3214TMX	Dual Non-Inverting Channels	TTL	SOIC-8	2,500 / Tape & Reel

DISCONTINUED (Note 12)

FAN3213TMX	Dual Inverting Channels	TTL	SOIC-8	2,500 / Tape & Reel
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[†] For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

12. **DISCONTINUED:** This device is not recommended for new design. Please contact your **onsemi** representative for information. The most current information on this device may be available on www.onsemi.com.

FAN3213, FAN3214

Table 1. RELATED PRODUCTS

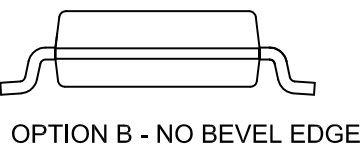
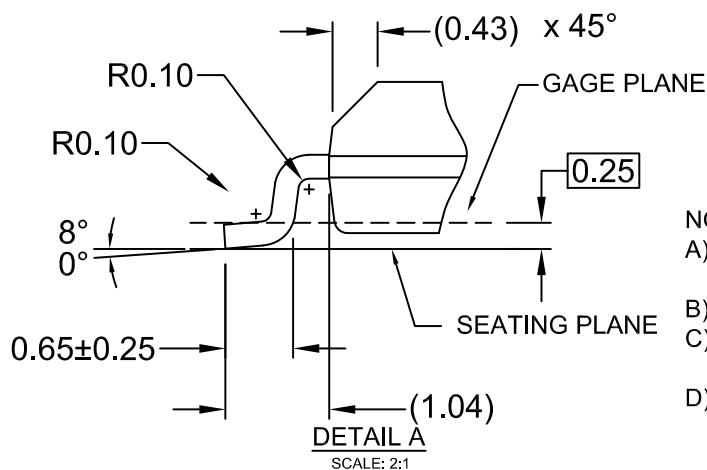
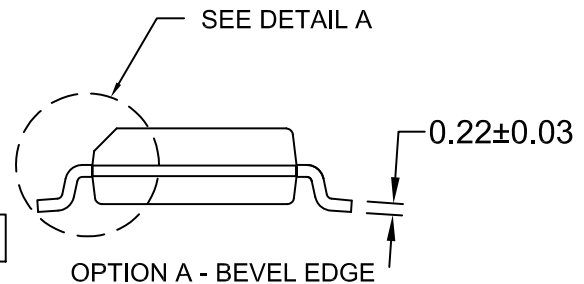
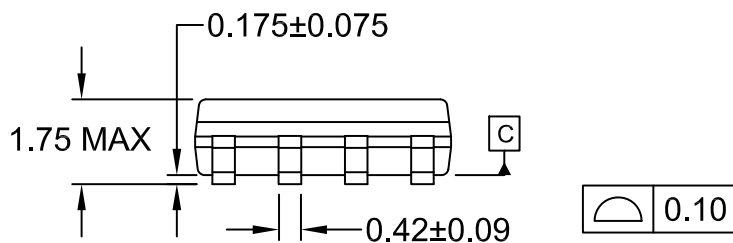
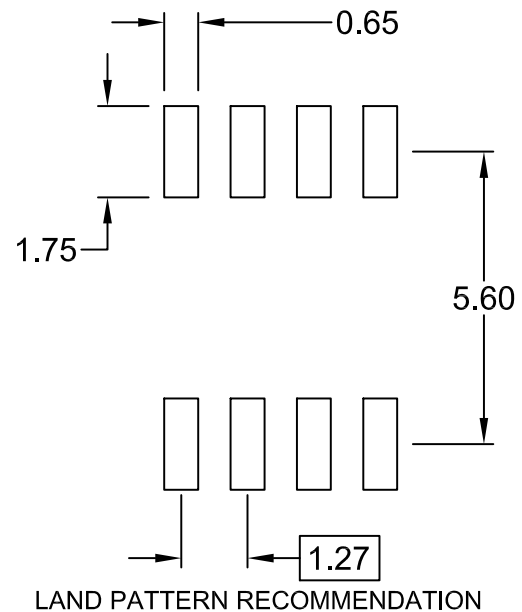
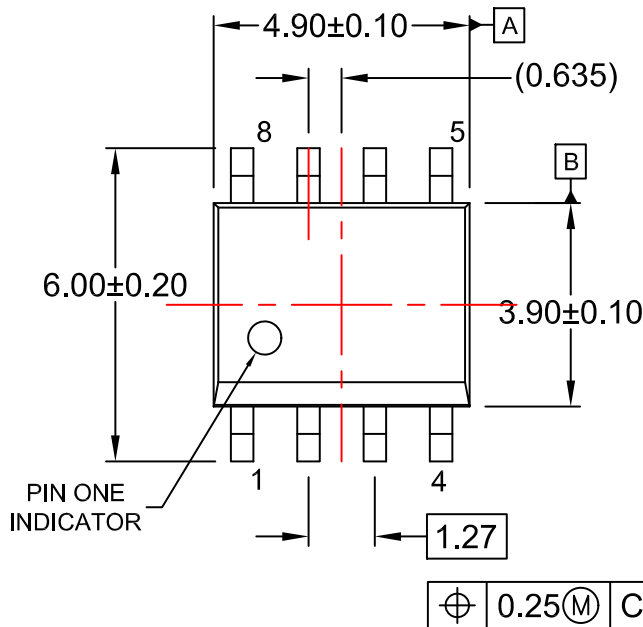
Type	Part Number	Gate Drive (Note 13) (Sink/Src)	Input Threshold	Logic	Package
Single 1 A	FAN3111C	+1.1 A / -0.9 A	CMOS	Single Channel of Dual-Input/Single-Output	SOT23-5, MLP6
Single 1 A	FAN3111E	+1.1 A / -0.9 A	External (Note 14)	Single Non-Inverting Channel with External Reference	SOT23-5, MLP6
Single 2 A	FAN3100C	+2.5 A / -1.8 A	CMOS	Single Channel of Two-Input/One-Output	SOT23-5, MLP6
Single 2 A	FAN3100T	+2.5 A / -1.8 A	TTL	Single Channel of Two-Input/One-Output	SOT23-5, MLP6
Single 2 A	FAN3180	+2.4 A / -1.6 A	TTL	Single Non-Inverting Channel + 3.3-V LDO	SOT23-5
Dual 2 A	FAN3216T	+2.4 A / -1.6 A	TTL	Dual Inverting Channels	SOIC8
Dual 2 A	FAN3217T	+2.4 A / -1.6 A	TTL	Dual Non-Inverting Channels	SOIC8
Dual 2 A	FAN3226C	+2.4 A / -1.6 A	CMOS	Dual Inverting Channels + Dual Enable	SOIC8, MLP8
Dual 2 A	FAN3226T	+2.4 A / -1.6 A	TTL	Dual Inverting Channels + Dual Enable	SOIC8, MLP8
Dual 2 A	FAN3227C	+2.4 A / -1.6 A	CMOS	Dual Non-Inverting Channels + Dual Enable	SOIC8, MLP8
Dual 2 A	FAN3227T	+2.4 A / -1.6 A	TTL	Dual Non-Inverting Channels + Dual Enable	SOIC8, MLP8
Dual 2 A	FAN3228C	+2.4 A / -1.6 A	CMOS	Dual Channels of Two-Input/One-Output, Pin Config.1	SOIC8, MLP8
Dual 2 A	FAN3228T	+2.4 A / -1.6 A	TTL	Dual Channels of Two-Input/One-Output, Pin Config.1	SOIC8, MLP8
Dual 2 A	FAN3229C	+2.4 A / -1.6 A	CMOS	Dual Channels of Two-Input/One-Output, Pin Config.2	SOIC8, MLP8
Dual 2 A	FAN3229T	+2.4 A / -1.6 A	TTL	Dual Channels of Two-Input/One-Output, Pin Config.2	SOIC8, MLP8
Dual 2 A	FAN3268T	+2.4 A / -1.6 A	TTL	20 V Non-Inverting Channel (NMOS) and Inverting Channel (PMOS) + Dual Enables	SOIC8
Dual 2 A	FAN3278T	+2.4 A / -1.6 A	TTL	30 V Non-Inverting Channel (NMOS) and Inverting Channel (PMOS) + Dual Enables	SOIC8
Dual 4 A	FAN3213T	+2.5 A / -1.8 A	TTL	Dual Inverting Channels	SOIC8
Dual 4 A	FAN3214T	+2.5 A / -1.8 A	TTL	Dual Non-Inverting Channels	SOIC8
Dual 4 A	FAN3223C	+4.3 A / -2.8 A	CMOS	Dual Inverting Channels + Dual Enable	SOIC8, MLP8
Dual 4 A	FAN3223T	+4.3 A / -2.8 A	TTL	Dual Inverting Channels + Dual Enable	SOIC8, MLP8
Dual 4 A	FAN3224C	+4.3 A / -2.8 A	CMOS	Dual Non-Inverting Channels + Dual Enable	SOIC8, MLP8
Dual 4 A	FAN3224T	+4.3 A / -2.8 A	TTL	Dual Non-Inverting Channels + Dual Enable	SOIC8, MLP8
Dual 4 A	FAN3225C	+4.3 A / -2.8 A	CMOS	Dual Channels of Two-Input/One-Output	SOIC8, MLP8
Dual 4 A	FAN3225T	+4.3 A / -2.8 A	TTL	Dual Channels of Two-Input/One-Output	SOIC8, MLP8
Single 9 A	FAN3121C	+9.7 A / -7.1 A	CMOS	Single Inverting Channel + Enable	SOIC8, MLP8
Single 9 A	FAN3121T	+9.7 A / -7.1 A	TTL	Single Inverting Channel + Enable	SOIC8, MLP8
Single 9 A	FAN3122C	+9.7 A / -7.1 A	CMOS	Single Non-Inverting Channel + Enable	SOIC8, MLP8
Single 9 A	FAN3122T	+9.7 A / -7.1 A	TTL	Single Non-Inverting Channel + Enable	SOIC8, MLP8
Dual 12 A	FAN3240	+12.0 A	TTL	Dual-Coil Relay Driver, Timing Config. 0	SOIC8
Dual 12 A	FAN3241	+12.0 A	TTL	Dual-Coil Relay Driver, Timing Config. 1	SOIC8

13. Typical currents with OUTx at 6 V and $V_{DD} = 12$ V.

14. Thresholds proportional to an externally supplied reference voltage.

SOIC8
CASE 751EB
ISSUE A

DATE 24 AUG 2017



NOTES:

- A) THIS PACKAGE CONFORMS TO JEDEC MS-012, VARIATION AA.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
- D) LANDPATTERN STANDARD: SOIC127P600X175-8M

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